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Claim Amendments

1. (currently amended) A method of packaging an integrated circuit die, comprising the steps of:
  - forming a plurality of soft conductive balls forms in a fixture, wherein opposing sides of the balls forms are at least partially flattened;
  - transferring the formed balls forms from the fixture to a mold masking tape;
  - attaching a first side of an integrated circuit die to the mold masking tape, wherein a second side of the die has a plurality of die bonding pads and wherein the die is surrounded by the formed balls forms;
  - electrically connecting the die bonding pads to respective ones of the formed balls forms surrounding the die;
  - encapsulating the die, the electrical connections, and a top portion of the formed balls forms with a mold compound; and
  - removing the mold masking tape such that a bottom portion portions of the balls forms are exposed.
2. (currently amended) The method of packaging an integrated circuit die of claim 1, wherein the balls forms formed in the fixture are spherical.
3. (currently amended) The method of packaging an integrated circuit die of claim 1, wherein the balls forms formed in the fixture are generally rectangular.
4. (currently amended) The method of packaging an integrated circuit die of claim 1, wherein ~~balls forming~~

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~~step includes the forms undergo~~ a mechanical coining step wherein ~~in~~ at least two opposing sides of the ~~balls~~ forms are at least partially flattened.

5. (currently amended) The method of packaging an integrated circuit die of claim 1, wherein an array of ~~balls~~ forms is formed in the fixture.

6. (currently amended) The method of packaging an integrated circuit die of claim 1, further comprising the ~~step of~~ attaching the mold masking tape to a frame.

7. (currently amended) The method of packaging an integrated circuit die of claim 1, wherein the die attaching step comprises attaching the first side of the die to a plurality of the ~~balls~~ forms with a die attach adhesive.

8. (currently amended) The method of packaging an integrated circuit die of claim 1, wherein the electrically connecting step comprises wirebonding the die bonding pads to the respective ones of the ~~balls~~ forms with a corresponding plurality of wires.

9. (currently amended) The method of packaging an integrated circuit die of claim 8, wherein in the wirebonding step, the wires penetrate into the ~~balls~~ forms and are embedded therein.

10. (original) The method of packaging an integrated circuit die of claim 9, wherein the wires are formed of copper, gold, or an alloy thereof.

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11. (currently amended) The method of packaging an integrated circuit die of claim 10, wherein the ~~balls~~ forms are formed of a metal that is softer than the wires so that the wires can be embedded into the ~~balls~~ forms.

12. (original) The method of packaging an integrated circuit die of claim 11, wherein the metal comprises solder or gold.

13. (original) The method of packaging an integrated circuit die of claim 1, further comprising the step of saw singulating the encapsulated die from adjacent encapsulated dice.

14. (currently amended) A method of packaging a plurality of integrated circuit dice, comprising the steps of:

forming a plurality of soft conductive ~~balls~~ forms in a fixture, wherein opposing sides of the ~~balls~~ forms are at least partially flattened;

transferring the formed ~~balls~~ forms from the fixture to a mold masking tape;

attaching first sides of the plurality of integrated circuit dice to the mold masking tape, wherein a second side of the dice have a plurality of die bonding pads and wherein each of the die is surrounded by some of the formed ~~balls~~ forms;

electrically connecting the die bonding pads of the dice to respective ones of the formed ~~balls~~ forms surrounding the dice;

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encapsulating the dice, the electrical connections, and a top portion of the formed ~~balls~~ forms with a mold compound;

removing the mold masking tape such that a bottom portions ~~portion~~ of the ~~balls~~ forms are exposed; and singulating the encapsulated dice to form individual packaged devices.

15. (currently amended) The method of packaging an integrated circuit die of claim 14, wherein the ~~balls~~ forms formed in the fixture are spherical.

16. (currently amended) The method of packaging an integrated circuit die of claim 14, wherein the ~~balls~~ forms formed in the fixture are generally rectangular.

17. (currently amended) The method of packaging an integrated circuit die of claim 14, wherein ~~balls~~ the forms undergo forming step ~~includes~~ a mechanical coining step ~~in~~ wherein at least two opposing sides of the balls are at least partially flattened.

18. (currently amended) The method of packaging an integrated circuit die of claim 14, wherein an array of ~~balls~~ forms is formed in the fixture.

19. (original) The method of packaging an integrated circuit die of claim 14, further comprising the step of attaching the mold masking tape to a frame.

20. (currently amended) The method of packaging an integrated circuit die of claim 14, wherein the dice

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attaching step comprises attaching the first side of the dice to a plurality of the ~~balls~~ forms with a die attach adhesive.

21. (currently amended) The method of packaging an integrated circuit die of claim 14, wherein the electrically connecting step comprises wirebonding the die bonding pads to the respective ones of the ~~balls~~ forms with a corresponding plurality of wires.

22. (currently amended) The method of packaging an integrated circuit die of claim 21, wherein in the wirebonding step, the wires penetrate the ~~balls~~ forms and are embedded therein.

23. (original) The method of packaging an integrated circuit die of claim 22, wherein the wires are formed of copper, gold, or an alloy.

24. (currently amended) The method of packaging an integrated circuit die of claim 23, wherein the ~~balls~~ forms are formed of a metal that is softer than the wires so that the wires can be embedded into the ~~balls~~ forms.

25. (original) The method of packaging an integrated circuit die of claim 24, wherein the metal comprises solder or gold.